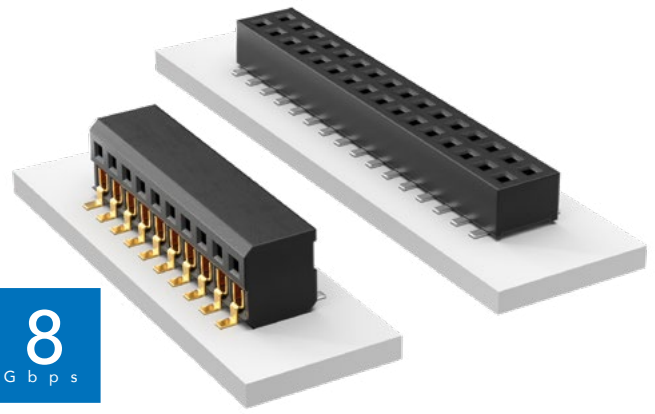


# LOW PROFILE DUAL WIPE SOCKET

(1.27 mm) .050" PITCH • CLP SERIES



## CLP

**Mates:**

FTSH, FTS, FW

| CLP | 1 | NO. PINS PER ROW | 02 | PLATING OPTION | ROW OPTION | OTHER OPTIONS |
|-----|---|------------------|----|----------------|------------|---------------|
|-----|---|------------------|----|----------------|------------|---------------|

02 thru 50

## SPECIFICATIONS

### Insulator Material:

Black Liquid Crystal Polymer

### Contact Material:

Phosphor Bronze

### Plating:

Sn or Au over

50 μ" (1.27 μm) Ni

### Current Rating (CLP/FTSH):

3.4 A per pin

(2 pins powered)

### Voltage Rating:

280 VAC/395 VDC

### Operating Temp Range:

-55 °C to +125 °C

### Insertion Depth:

Top Entry =

(1.40 mm) .055" minimum

Bottom Entry =

(2.41 mm) .095" minimum

plus board thickness

DH Entry =

(2.31 mm) .091" to (2.67 mm) .105"

### Max Cycles:

100 with 10 μ" (0.25 μm) Au

## PROCESSING

### Lead-Free Solderable:

Yes

### SMT Lead Coplanarity:

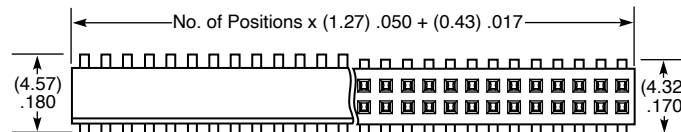
(0.10 mm) .004" max (02-35)

(0.15 mm) .006" max (36-50)\*

\*(.004" stencil solution

may be available; contact

ipg@samtec.com)



## ALSO AVAILABLE

MOQ Required

Single row

Other platings

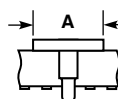


## Notes:

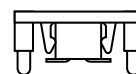
Severe Environment  
Testing qualified; aligns  
with MIL-DTL-55302.  
Visit [samtec.com/set](http://samtec.com/set)

Some lengths, styles and  
options are non-standard,  
non-returnable.

| PIN/ROW | A           |
|---------|-------------|
| 04-15   | (3.56) .140 |
| 16-50   | (7.11) .280 |



If odd pins/row, alignment pins are on  
middle position on centerline of the part.  
If even pins/row, then alignment pins are  
between middle two positions.



-PA OPTION



-P OPTION